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Please note: As part of the Fairchild Semiconductor integration, some of the Fairchild orderable part numbers will need to change in order to meet ON Semiconductor's system requirements. Since the ON Semiconductor product management systems do not have the ability to manage part nomenclature that utilizes an underscore (_), the underscore (_) in the Fairchild part numbers will be changed to a dash (-). This document may contain device numbers with an underscore (_). Please check the ON Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.onsemi.com. Please email any questions regarding the system integration to Fairchild guestions@onsemi.com.

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April 2015

FDD770N15A

N-Channel PowerTrench[®] MOSFET 150 V, 18 A, 77 m Ω

Features

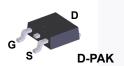
- $R_{DS(on)}$ = 61 m Ω (Typ.) @ V_{GS} = 10 V, I_D = 12 A
- · Fast Switching Speed
- · Low Gate Charge
- High Performance Trench Technology for Extremely Low $R_{\text{DS(on)}}$
- · High Power and Current Handling Capability
- · RoHS Compliant

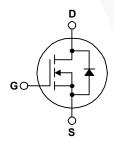
Description

This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench® process that has been tailored to minimize the on-state resistance while maintaining superior switching performance.

Applications

- · DC to DC Converters
- · Synchronous Rectification for Server / Telecom PSU
- · Battery Charger
- · AC motor drives and Uninterruptible Power Supplies
- · Off-line UPS





Absolute Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol		Parameter	FDD770N15A	Unit
V _{DSS}	Drain to Source Voltage		150	V
V	Cata to Course Voltage	- DC	±20	V
V_{GSS}	Gate to Source Voltage	- AC (f > 1 Hz)	±30	V
I _D	Drain Current	- Continuous (T _C = 25°C, Silicon Limited)	18	А
	Drain Current	- Continuous (T _C = 100°C, Silicon Limited)	11.4	_ A
I _{DM}	Drain Current	- Pulsed (Note 1)	36	Α
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	31.7	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	6.0	V/ns
D	Pawer Dissipation	$(T_C = 25^{\circ}C)$	56.8	W
P_{D}	Power Dissipation - Derate Above 25°C		0.46	W/°C
T _J , T _{STG}	Operating and Storage Temperat	-55 to +150	°C	
T _I	Maximum Lead Temperature for	Soldering, 1/8" from Case for 5 Seconds	300	οС

Thermal Characteristics

Symbol	Parameter	FDD770N15A	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	2.2	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	87	°C/VV

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FDD770N15A	FDD770N15A	DPAK	Tape and Reel	330 mm	16 mm	2500 units

Electrical Characteristics $T_C = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	cteristics					
BV _{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	150	-	-	V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I_D = 250 μA, Referenced to 25°C	-	0.0824	-	V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 120 V, V _{GS} = 0 V	-	-	1	
		V_{DS} = 120 V, V_{GS} = 0 V, T_{C} = 125°C	-	-	500	μΑ
I _{GSS}	Gate to Source Leakage Current	V _{GS} = ±20 V, V _{DS} = 0 V	-	-	±100	nA

On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	2.0	-	4.0	V
R _{DS(on)}	Static Drain to Source On Resistance	V _{GS} = 10 V, I _D = 12 A	1	61	77	mΩ
g _{FS}	Forward Transconductance	V _{DS} = 10 V, I _D = 12 A	-	20	-	S

Dynamic Characteristics

C _{iss}	Input Capacitance	.,	-	575	765	pF
C _{oss}	Output Capacitance	$V_{DS} = 75 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1 MHz	-	64	85	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1 1011 12	-	3.9	6	pF
C _{oss(er)}	Energy Related Output Capacitance	V _{DS} = 75 V, V _{GS} = 0 V	- \	113	-	pF
Q _{g(tot)}	Total Gate Charge at 10V		- \	8.4	11	nC
Q _{gs}	Gate to Source Gate Charge	$V_{DS} = 75 \text{ V}, I_{D} = 12 \text{ A},$	-	2.7	-	nC
Q_{gd}	Gate to Drain "Miller" Charge	V _{GS} = 10 V	-	1.8	-	nC
V _{plateau}	Gate Plateau Volatge	(Note	4) -	5.7	-	V
Q _{sync}	Total Gate Charge Sync.	V _{DS} = 0 V, I _D = 6 A	-	6.9	-	nC
Q _{oss}	Output Charge	V _{DS} = 37.5 V, V _{GS} = 0 V	-	14	-	nC
ESR	Equivalent Series Resistance (G-S)	f = 1 MHz	-	0.5	-	Ω

Switching Characteristics

t _{d(on)}	Turn-On Delay Time		-	10.3	30.6	ns
t _r	Turn-On Rise Time	V _{DD} = 75 V, I _D = 12 A,	-	3.1	16.2	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = 10 \text{ V}, R_G = 4.7 \Omega$	-	15.8	41.6	ns
t _f	Turn-Off Fall Time	(Note 4)	-	2.8	15.6	ns

Drain-Source Diode Characteristics

I _S	Maximum Continuous Drain to Source Diode Forward Current			-	18	Α
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current			- /	36	Α
V_{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0 V, I _{SD} = 12 A	-	-	1.25	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, V _{DD} = 75 V, I _{SD} = 12 A,	-	56.4	//	ns
Q _{rr}	Reverse Recovery Charge	$dI_F/dt = 100 A/\mu s$	-	109	1 -	nC

Notes

- ${\it 1. Repetitive\ rating: pulse-width\ limited\ by\ maximum\ junction\ temperature.}$
- 2. L = 3 mH, I_{AS} = 4.6 A, starting T_J = 25°C.
- 3. $I_{SD} \le$ 12 A, di/dt \le 200 A/ μ s, $V_{DD} \le$ BV $_{DSS}$, starting T $_{J}$ = 25°C.
- 4. Essentially independent of operating temperature typical characteristics.

Typical Performance Characteristics

Figure 1. On-Region Characteristics

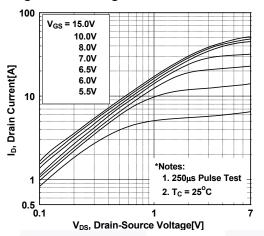


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

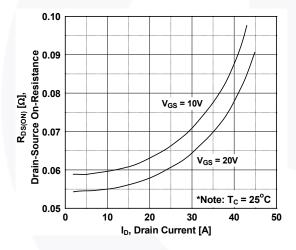


Figure 5. Capacitance Characteristics

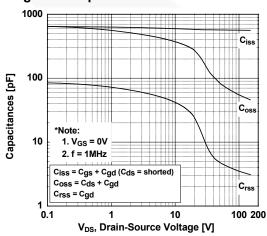


Figure 2. Transfer Characteristics

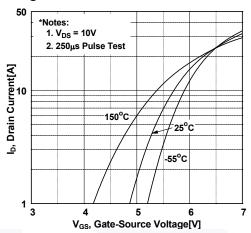


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

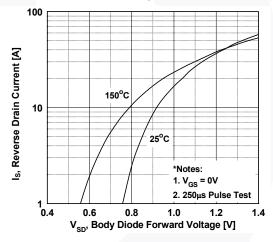
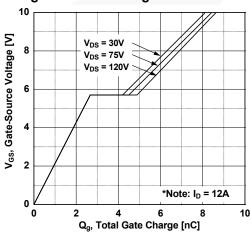


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

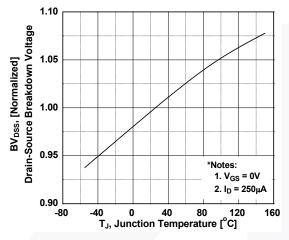


Figure 9. Maximum Safe Operating Area

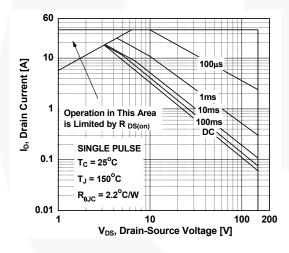


Figure 11. Eoss vs. Drain to Source Voltage

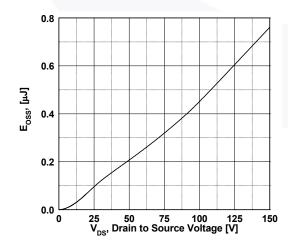


Figure 8. On-Resistance Variation vs. Temperature

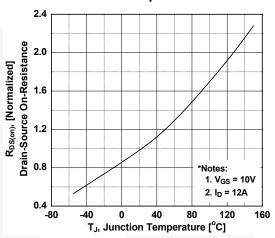


Figure 10. Maximum Drain Current vs. Case Temperature

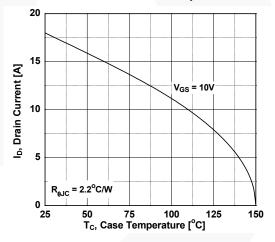
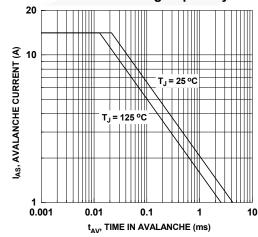
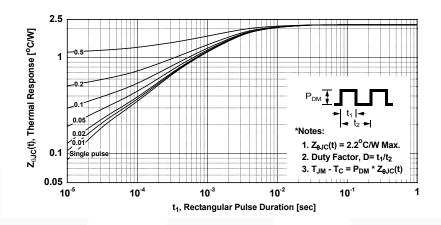


Figure 12. Unclamped Inductive Switching Capability



Typical Performance Characteristics (Continued)

Figure 13. Transient Thermal Response Curve



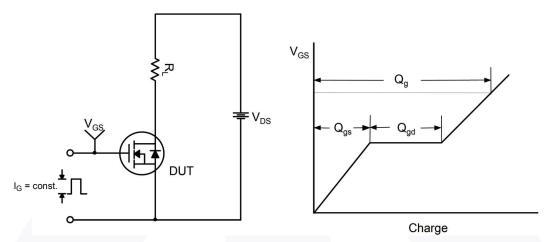


Figure 14. Gate Charge Test Circuit & Waveform

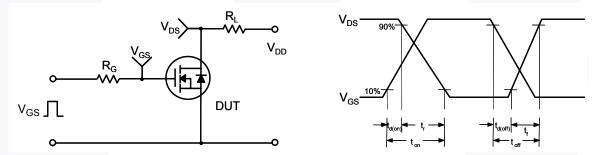


Figure 15. Resistive Switching Test Circuit & Waveforms

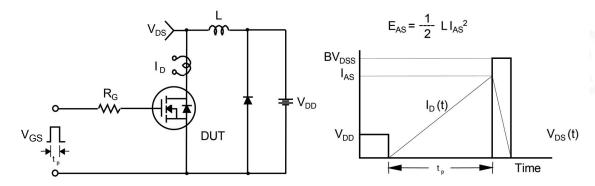


Figure 16. Unclamped Inductive Switching Test Circuit & Waveforms

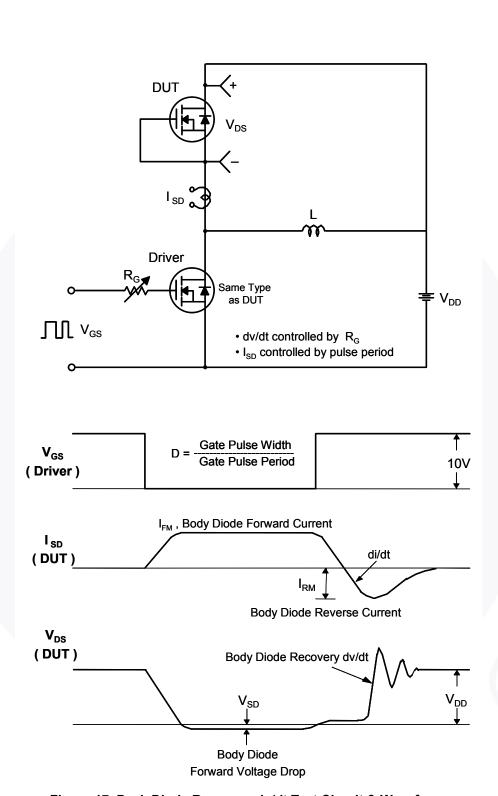


Figure 17. Peak Diode Recovery dv/dt Test Circuit & Waveforms

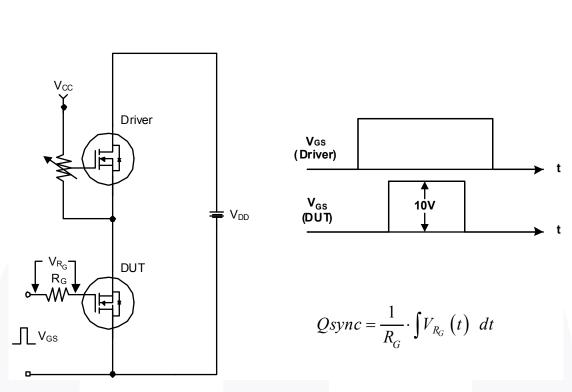


Figure 18. Total Gate Charge Qsync. Test Circuit & Waveforms



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